VRetnasamy

List of Publications by Year
in descending order

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93 papers	155 citations	2942236 2 h-index	2266119 5 g-index
93 all docs	93 docs citations	93 times ranked	65 citing authors

#	Article	IF	Citations
1	Motion behavior of mammalian AT-SC under evanescent field illumination. , 2015, , .		0
2	Effect of barrier materials on the polarization field in the active region of blue InGaN LED using Sentaurus. Proceedings of SPIE, 2015, , .	0.8	0
3	Quantum well thickness variation investigation on optical and thermal performances of GaN LEDs. , 2015, , .		1
4	Quantum barrier thickness study on blue InGaN LED optical performance using Sentaurus. , 2015, , .		1
5	Critical analysis on degradation mechanism of dye-sensitized solar cells. , 2015, , .		0
6	Interaction Relationship Analysis of Surface Roughness on Aluminium Etched Wafer Using RIE. Applied Mechanics and Materials, 2014, 487, 214-217.	0.2	0
7	Bond Strength Comparison between Silicon and Glass Based Surface Using Anodic Bonding. Applied Mechanics and Materials, 2014, 680, 89-92.	0.2	1
8	Investigation of Surface Roughness on Platinum Deposited Wafer after Reactive Ion Etching Using SF₆+Argon Gaseous. Applied Mechanics and Materials, 2014, 487, 210-213.	0.2	0
9	Metallic Layer Reflectance Analysis Using Design of Experiment. Advanced Materials Research, 2014, 893, 461-464.	0.3	0
10	Reflectance Analysis of Sputtered Indium Tin Oxide(ITO) Using UV Lambda. Applied Mechanics and Materials, 2014, 680, 102-105.	0.2	0
11	High Power LED Heat Dissipation Comparison Analysis via Aluminum and Copper Slug. Advanced Materials Research, 2014, 893, 811-814.	0.3	1
12	Height Measurement Based on Fringe Projection. Applied Mechanics and Materials, 2014, 487, 298-301.	0.2	0
13	CuDia Slug Size Variation Analysis on Heat Dissipation of High Power LED. Applied Mechanics and Materials, 2014, 487, 33-36.	0.2	2
14	3D Shape Measurement and Reconstruction Using Fringe Projection. Applied Mechanics and Materials, 2014, 487, 572-575.	0.2	0
15	Surface Roughness Scrutinizaton with RIE CF₄+Argon Gaseous on Platinum Deposited Wafer. Applied Mechanics and Materials, 2014, 487, 71-74.	0.2	0
16	Surface Roughness and Wettability Correlation on Etched Platinum Using Reactive Ion Ecthing. Applied Mechanics and Materials, 2014, 487, 263-266.	0.2	1
17	Preliminary Study on Resistance of Non-Treated and Treated ITO Films. Applied Mechanics and Materials, 2014, 680, 111-114.	0.2	0
18	High Heat Treatment Analysis on Ba _{0.6}Sr _{0.4}TiO₃ Thin Films. Advanced Materials Research, 2014, 893, 550-553.	0.3	0

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19	LED Heat Dissipation Analysis Using Composite Based Cylindrical Slug. Advanced Materials Research, 2014, 893, 803-806.	0.3	1
20	Deposition Time Variation Analysis on Indium Tin Oxide Film. Advanced Materials Research, 2014, 893, 562-565.	0.3	0
21	Ba_xSr_{1-x} TiO₃ Different Thickness Analysis Using Sol Gel Approach. Applied Mechanics and Materials, 2014, 487, 29-32.	0.2	0
22	Hydrophilicity Characterization on Cleaned Bonded Silicon Based Surface. Applied Mechanics and Materials, 2014, 680, 127-130.	0.2	0
23	Natural Heat Convection Analysis on Cylindrical Al Slug of LED. Applied Mechanics and Materials, 2014, 487, 536-539.	0.2	3
24	Effects of Heat Slug Shapes on the Heat Dissipation of High Power LED. Advanced Materials Research, 2014, 893, 807-810.	0.3	0
25	Main Effects of Lattice Parameter in Ba0.65Sr0.35TiO3 Thin Films. Procedia, Social and Behavioral Sciences, 2014, 129, 512-517.	0.5	0
26	Microfluidic channel depth determination with Tywmanâ€“Green interferometer. International Journal of Advanced Manufacturing Technology, 2013, 67, 851-855.	1.5	2
27	Solid State Lighting Stress and Junction Temperature Evaluation on Operating Power. , 2013, , .		5
28	Different Shear Height Stress Evaluation on -0.7Cu Based Lead Free Solder. , 2013, , .		2
29	Shear Ram Speed Analysis for Gold Wire Bond Shear Test. , 2013, , .		0
30	Large Sized Slug on Solid State Lighting Stress and Temperature Analysis. , 2013, , .		0
31	Higher Copper Composition Shear Stress Analysis on Lead Free Solder Ball. , 2013, , .		0
32	Finite Element Analysis on Sn-3.9Ag-0.6Cu and Sn-3.5Ag-0.7Cu Using Different Shearing Height. , 2013, , .		0
33	Ionic contaminations level and cleaning flip chip BGA package via a new cleaning solvent technology. Microelectronics International, 2013, 30, 99-103.	0.4	0
34	Finite element analysis of thermal distributions of solder ball in flip chip ball grid array using ABAQUS. Microelectronics International, 2013, 30, 14-18.	0.4	8
35	5mm X 5mm Copper-Diamond Composite Slug Stress Evaluation on LED. , 2013, , .		4
36	Stress and Temperature Simulation Using Copper-Diamond Composite Slug. , 2013, , .		2

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37	Shear Height Analysis Study on Sn-3.9Ag-0.6Cu by Using SSF Method. , 2013, , .		0
38	High Power LED Thermal and Stress Simulation on Copper Slug. , 2013, , .		6
39	Shearing Speed Stress Comparison between Sn-3.9Ag-0.6Cu and Sn-3.5Ag-0.7Cu Solder Ball. , 2013, , .		1
40	Single hole at constrained location for stress analysis in PCB plate bending. , 2012, , .		0
41	Stress Analysis on Through Holes in PCB. , 2012, , .		6
42	Stress analysis on centric through hole PCB. , 2012, , .		0
43	Gold and Copper Ball Bond Shear Stress Comparison At Different Shear Tool Heights. , 2012, , .		3
44	Effect of copper FAB impact on palladium bond pad. , 2012, , .		1
45	Shear Stress Analysis Study Using Surface Morphology Correlation with Aluminium Ball Adhesion. , 2012, , .		10
46	2D Velocity Streamline Visualization of Microfluid Flow in Backward Facing Step Microchannel. , 2012, , .		1
47	Polymer Core BGA Vertical Stress Loading Analysis. , 2012, , .		5
48	Shearing Speed Induced Stress Comparison on Gold and Copper Ball Interconnection. , 2012, , .		9
49	Interaction of Surface Roughness and Copper Ball Adhesion Using Shearing Simulation. , 2012, , .		11
50	Flux residue cleaning process optimization effect on Flip Chip Ball Grid Array reliability. , 2012, , .		1
51	Gold Ball Shear Stress Analysis on Different Surface Morphology. , 2012, , .		6
52	The role of Reactive Ion Etching(RIE) on wirebond formation: A study on successful rate of thermosonic gold wire on aluminium bondpad. , 2012, , .		2
53	Velocity Profiles of Liquid Flow in Backward Facing Step Microchannel. , 2012, , .		0
54	Microchannel miter bend effects on pressure equalization and vortex formation. Microsystem Technologies, 2011, 17, 469-475.	1.2	2

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55	Phase-map fringe pixel tracing for height computation. , 2010, , .		2
56	No Slip and Free Slip Boundary Conditions for Liquid Flow in Obstructed Straight Microchannel. , 2010, , .		0
57	Entrance Length Observation for Water Flow in Microchannels with Surface Irregularities. , 2010, , .		0
58	Measurement of PCI connector tilts using phase-shift fringe projection. International Journal of Advanced Manufacturing Technology, 2008, 38, 1172-1180.	1.5	9
59	Complex background subtraction for biometric identification. , 2007, , .		4
60	Advanced computational geometry for proximity queries of convex polyhedras. , 2007, , .		1
61	Shear Ram Height Investigation for Gold Wire Bond Shear Test. Advanced Materials Research, 0, 622-623, 1447-1450.	0.3	5
62	Wire Bond Shear Test Simulation on Hemispherical Surface Bond Pad. Advanced Materials Research, 0, 622-623, 643-646.	0.3	4
63	Wire Bond Shear Test Simulation on Sharp Groove Surface Bond Pad. Advanced Materials Research, 0, 622-623, 647-651.	0.3	11
64	Polymer Core BGA Stress Analysis at Minimal Vertical Loading. Advanced Materials Research, 0, 622-623, 639-642.	0.3	8
65	Shear Ram Speed Characterization for Copper Wire Bond Shear Test. Applied Mechanics and Materials, 0, 229-231, 670-673.	0.2	0
66	Shear Ram Height Characterization for Copper Wire Bond Shear Test. Applied Mechanics and Materials, 0, 229-231, 674-677.	0.2	1
67	5mm Ã— 5mm Sized Slug on High Power LED Stress and Junction Temperature Analysis. Applied Mechanics and Materials, 0, 404, 460-464.	0.2	0
68	Bump Height at Low Temperature Analysis. Applied Mechanics and Materials, 0, 404, 77-81.	0.2	0
69	Relationship between Controllable Process Parameters on Bump Height in ENIG. Applied Mechanics and Materials, 0, 404, 62-66.	0.2	2
70	Shear Speed Analysis on Sn-3.9Ag-0.6Cu Solder. Applied Mechanics and Materials, 0, 404, 72-76.	0.2	0
71	Aluminium Surface Grain Size Analysis on RIE Treatment. Applied Mechanics and Materials, 0, 404, 67-71.	0.2	2
72	Velocity Profile Investigation of FFS Microchannel at Re 100. Applied Mechanics and Materials, 0, 487, 290-293.	0.2	0

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73	Contact Angle Analysis on Glass Based Surface. Applied Mechanics and Materials, 0, 680, 93-96.	0.2	1
74	Wettability Study Using O<sub>2 </sub>and Ar RIE Gas Treatment on Aluminium Surface. Advanced Materials Research, 0, 896, 233-236.	0.3	0
75	Reactive Ion Etching Parameter Effect on Aluminum Bond Pad Surface Morphology. Advanced Materials Research, 0, 925, 140-143.	0.3	0
76	Surface Roughness Influence on O<sub>2 </sub>and Ar RIE Gas Treated Aluminum Surface. Advanced Materials Research, 0, 925, 92-95.	0.3	0
77	Effect of High Temperature during Electroless Nickel Process. Advanced Materials Research, 0, 925, 88-91.	0.3	0
78	WSS Investigation in Microfluidic FFS Channel at Re 500. Applied Mechanics and Materials, 0, 487, 294-297.	0.2	1
79	Heat Sink Fin Number Variation Analysis on Single Chip High Power LED. Applied Mechanics and Materials, 0, 487, 149-152.	0.2	2
80	Main Effects Study on Plasma Etched Aluminium Metallization. Applied Mechanics and Materials, 0, 487, 195-198.	0.2	0
81	Fibrous Material Surface Reflectance Analysis. Applied Mechanics and Materials, 0, 487, 90-93.	0.2	0
82	Grain Size Analysis on Ba<sub>0.65</sub>Sr<sub>0.35</sub>TiO<sub>3</sub> Thin Films Using Design of Experiment. Advanced Materials Research, 0, 896, 211-214.	0.3	2
83	Wettability and Surface Roughness Study on RIE Treated Aluminium Deposited Surface. Advanced Materials Research, 0, 925, 101-104.	0.3	0
84	Reactive Ion Etching Parameter Effect on Aluminum Bond Pad Surface Morphology. Advanced Materials Research, 0, 925, 84-87.	0.3	0
85	Chemical Bath Temperature Investigation for Electroless Nickel Immersion Gold. Advanced Materials Research, 0, 925, 96-100.	0.3	0
86	Fibrous Material Density Difference Analysis Using Light Reflectance. Applied Mechanics and Materials, 0, 487, 114-117.	0.2	0
87	Quantitative Bump Height Analysis in ENIG Using Design of Experiment. Advanced Materials Research, 0, 896, 660-663.	0.3	0
88	Thermal Stress Comparison on Copper and Gold Wire Bonded on Aluminium Bondpad. Advanced Materials Research, 0, 1082, 323-326.	0.3	0
89	Surface Roughness and Grain Size Analysis of Treated Indium Tin Oxide(ITO)Film. Applied Mechanics and Materials, 0, 680, 131-134.	0.2	0
90	Physical Characterization of BST with Different (xâ€™) Ratios. Applied Mechanics and Materials, 0, 487, 106-109.	0.2	0

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91	Surface Roughness Analysis on Reactive Ion Etched Aluminium Deposited Wafer. Applied Mechanics and Materials, 0, 487, 141-144.	0.2	0
92	Operating Temperature Analysis of LED with Cylindrical Cu Slug. Applied Mechanics and Materials, 0, 487, 145-148.	0.2	2
93	Analysis on Surface Roughness and Surface Reflectance through DOE. Applied Mechanics and Materials, 0, 487, 37-40.	0.2	0